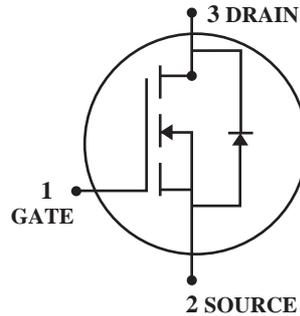


N-Channel Enhancement Mode Power MOSFET

 Lead(Pb)-Free

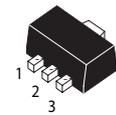


DRAIN CURRENT
5.0 AMPERES

DRAIN SOURCE VOLTAGE
60 VOLTAGE

Features:

- * Simple Drive Requirement.
- * Super High Density Cell Design for Extremely Low $R_{DS(ON)}$.



1. GATE
2. DRAIN
3. SOURCE

SOT-89

Maximum Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Specified)

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$ 5.0 $T_A=70^\circ\text{C}$ 4.0	A
Pulsed Drain Current	I_{DM}	10	A
Total Power Dissipation ($T_A=25^\circ\text{C}$)	P_D	1.50	W
Maximum Junction-Ambient ³	$R_{\theta JA}$	83.3	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	T_J	-55~+150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55~+150	$^\circ\text{C}$

Note 1. Pulse width limited by Max. junction temperature.

2. Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

3. Surface mounted on FR4 board, $t \leq 10\text{sec}$.

Device Marking

WTM2310A = 2310A

Electrical Characteristics (T_j = 25°C unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	60	-	-	V	$V_{GS}=0, I_D=250\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	0.5	-	1.5	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Forward Transconductance	g_{fs}	-	12	-	S	$V_{DS}=15V, I_D=4A$
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{GS}= \pm 20V$
Drain-Source Leakage Current(T _j =25°C)	I_{DSS}	-	-	1	μA	$V_{DS}=60V, V_{GS}=0$
Drain-Source Leakage Current(T _j =55°C)		-	-	10	μA	$V_{DS}=60V, V_{GS}=0$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	-	115	m Ω	$V_{GS}=10V, I_D=5.0A$
		-	-	125		$V_{GS}=4.5V, I_D=4.5A$
Total Gate Charge ²	Q_g	-	4.0	-	nC	$I_D=4A$ $V_{DS}=30V$ $V_{GS}=4.5V$
Gate-Source Charge	Q_{gs}	-	1.2	-		
Gate-Drain ("Miller") Change	Q_{gd}	-	1.0	-		
Turn-on Delay Time ²	$T_{d(on)}$	-	6	-	ns	$V_{DD}=30V$ $I_D=2.5A$ $V_{GS}=10V$ $R_G=6\Omega$ $R_L=12\Omega$
Rise Time	T_r	-	12	-		
Turn-off Delay Time	$T_{d(off)}$	-	18	-		
Fall Time	T_f	-	10	-		
Input Capacitance	C_{iss}	-	320	-	pF	$V_{GS}=0V$ $V_{DS}=30V$ $f=1.0MHz$
Output Capacitance	C_{oss}	-	42	-		
Reverse Transfer Capacitance	C_{rss}	-	20	-		

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage ²	V_{SD}	-	-	1.2	V	$I_S=2.5A, V_{GS}=0V$

Notes: 1. Pulse width limited by Max. junction temperature.

2. Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

3. Surface mounted on FR4 board, $t \leq 10sec$.

Characteristics Curve

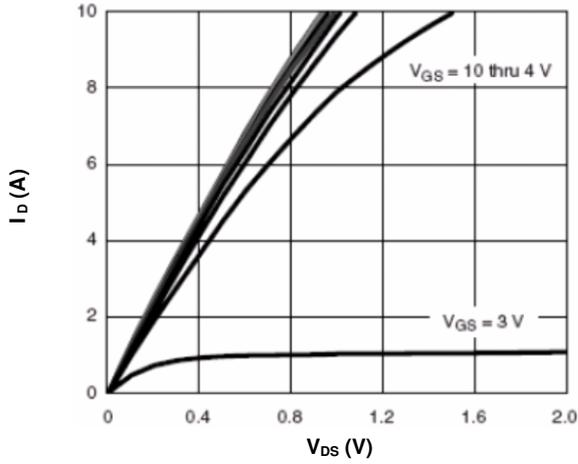


Fig 1. Typical Output Characteristics

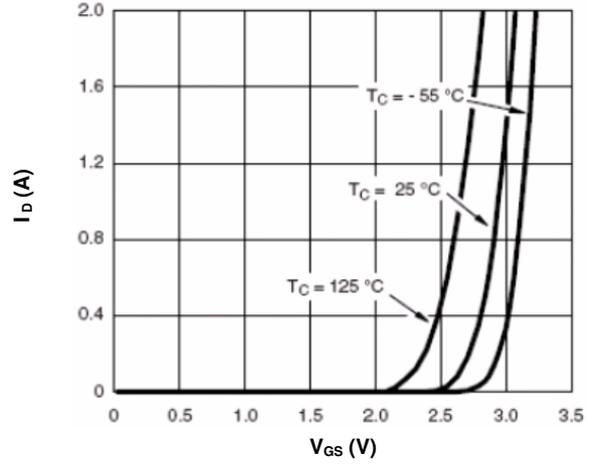


Fig 2. Transfer Characteristics

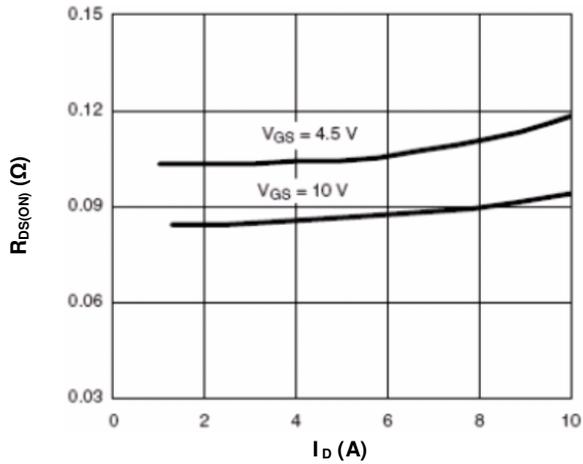


Fig 3. On-Resistance vs. Drain Current and Gate Voltage

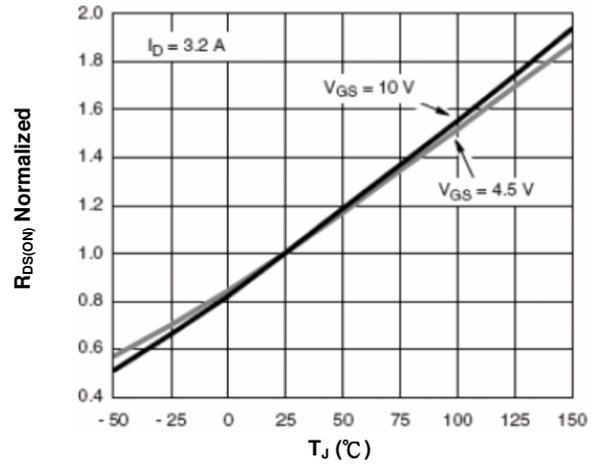


Fig 4. On-Resistance vs. Junction Temperature

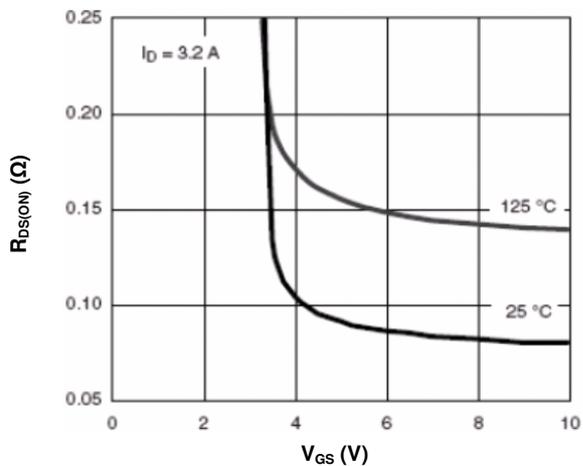


Fig 5. On-Resistance vs. Gate-Source Voltage

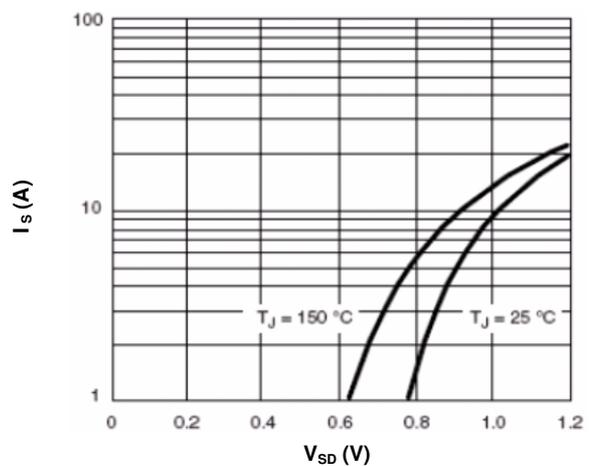


Fig 6. Body Diode Characteristics

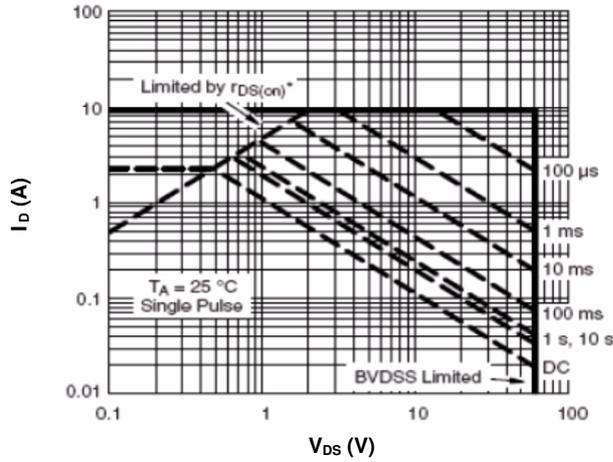


Fig 7. Maximum Safe Operating Area

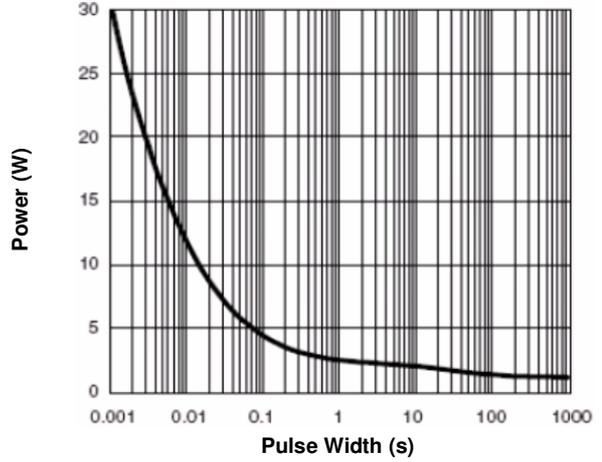


Fig 8. Single Pulse Maximum Power Dissipation

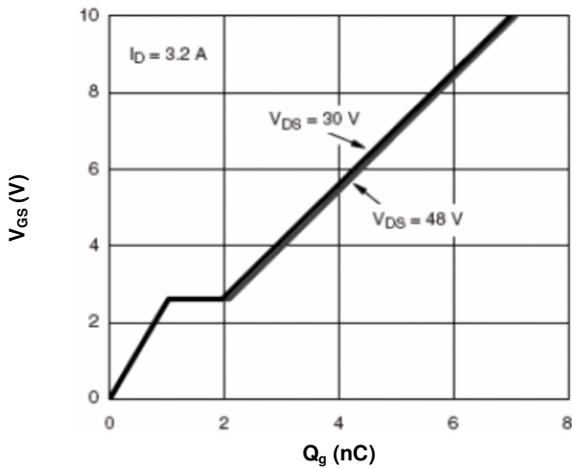


Fig 9. Gate Charge Characteristics

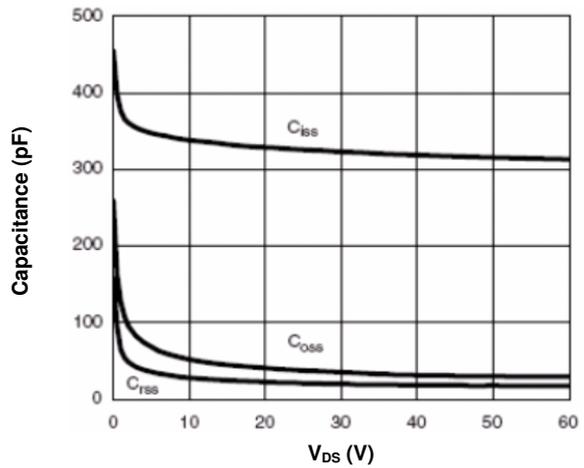


Fig 10. Typical Capacitance Characteristics

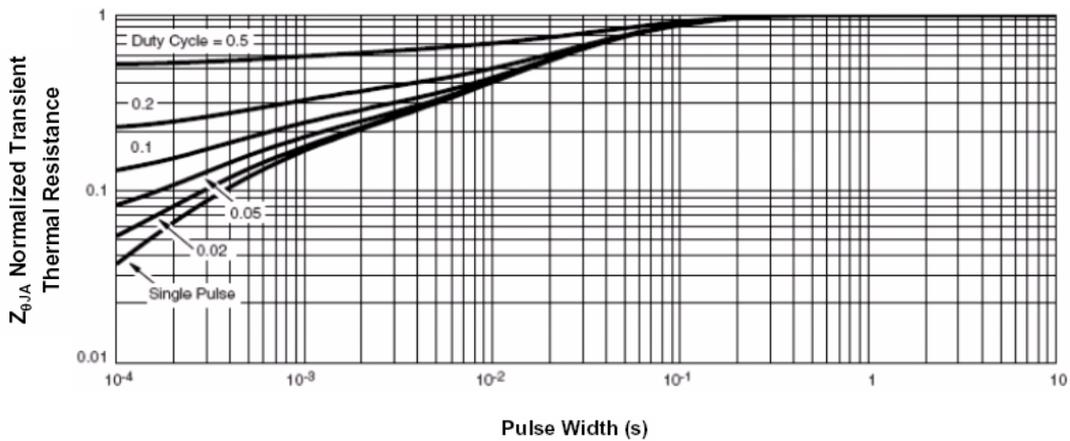
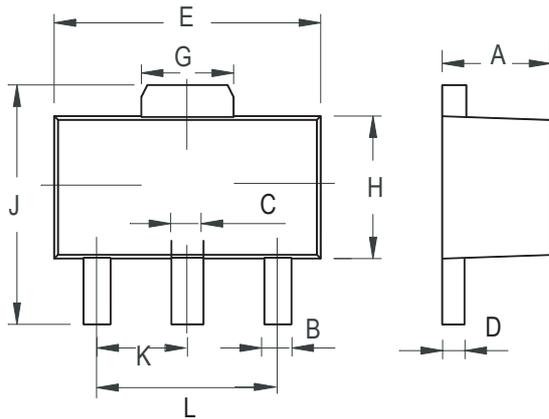


Fig 11. Normalized Maximum Transient Thermal Impedance

SOT-89 Outline Dimensions

unit:mm



SOT-89		
Dim	Min	Max
A	1.400	1.600
B	0.320	0.520
C	0.360	0.560
D	0.350	0.440
E	4.400	4.600
G	1.400	1.800
H	2.300	2.600
J	3.940	4.250
K	1.500TYP	
L	2.900	3.100